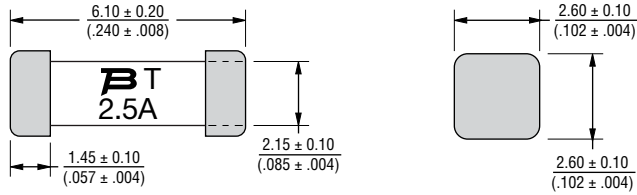


# SF-2410HI-T Series – High Inrush SMD Fuses

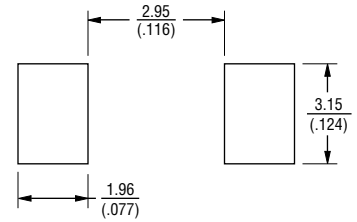
**BOURNS®**

## Product Dimensions



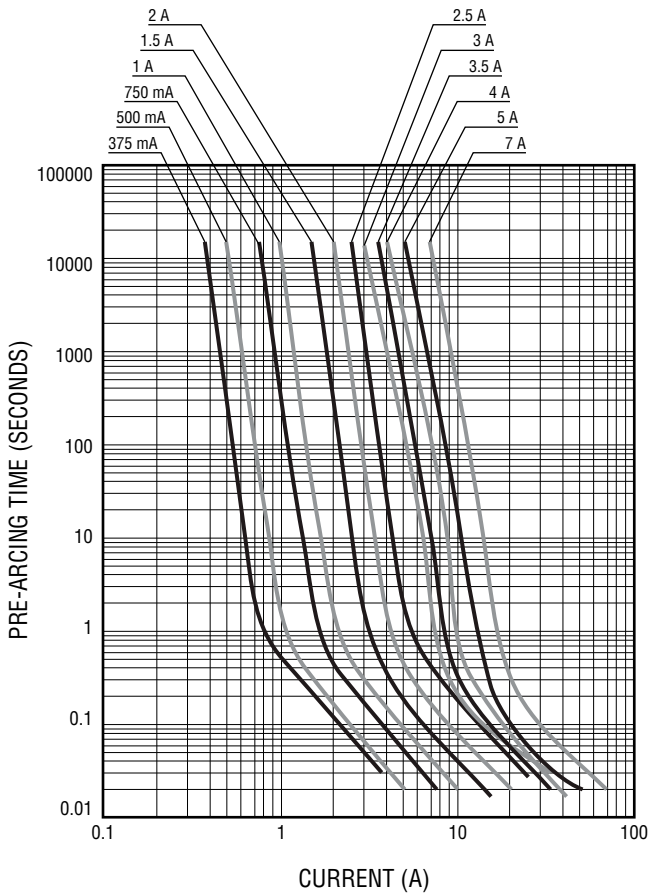
DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

## Recommended Pad Layout

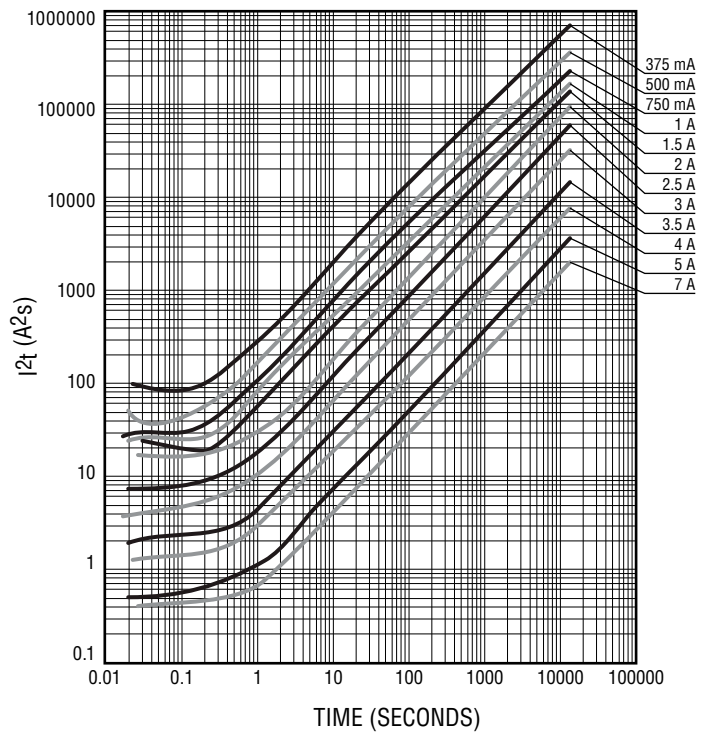


DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

## Average Pre-Arcing Time vs. Current Curves



## Average I<sup>2</sup>t vs. t Curves

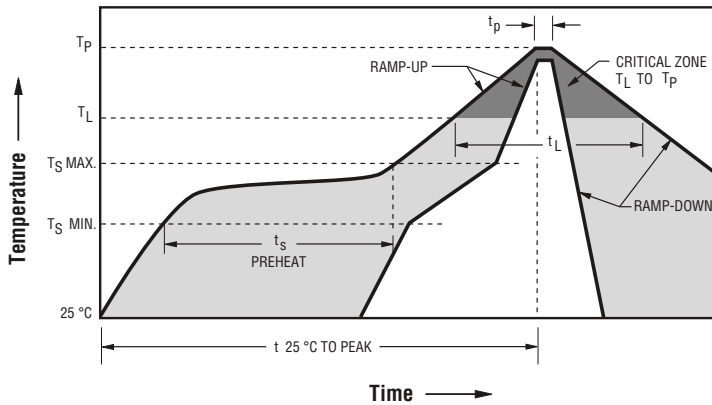


Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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## Solder Reflow Recommendations

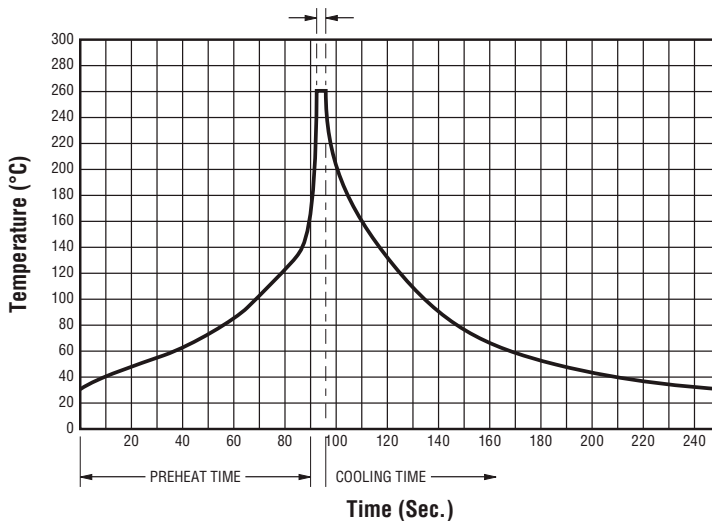


Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T <sub>smin</sub> ) Temperature Max. (T <sub>smax</sub> ) Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	150 °C 200 °C 60~180 seconds
Ramp Up Rate (T <sub>L</sub> to T <sub>p</sub> )	3 °C / second max.
Ramp Up Rate (T <sub>smax</sub> to T <sub>L</sub> )	5 °C / second max.
Liquidous Temperature (T <sub>L</sub> ) Time (t <sub>L</sub> ) maintained above T <sub>L</sub>	217 °C 60~90 seconds
Peak Package Body Temperature (T <sub>p</sub> )	235 °C ± 5 °C
Time within 5 °C of actual peak temperature (T <sub>p</sub> )	20~30 seconds*
Ramp Down Rate (T <sub>p</sub> to T <sub>L</sub> )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	240 °C

\* Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.

## Solder Wave Recommendations

Peak Temperature (Dwell Time)



Profile Feature	Pb-Free Assembly
Preheat: Temperature Max. (T <sub>smax</sub> ) Time (Min. to Max.)	150 °C 60~90 seconds
Solder Pot Temperature	260 °C max.
Solder Dwell Time	2~3 seconds

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